



**THE DATASHEET OF
LM64CILQ-F/NOPB**



LM64 $\pm 1^\circ\text{C}$ Remote Diode Temperature Sensor with PWM Fan Control and 5 GPIO's

Check for Samples: [LM64](#)

FEATURES

- Accurately Senses Remote and Local Diode Temperatures
- Integrated PWM Fan Speed Control Output
- Programmable 8-step Lookup Table for Quieting Fans
- $\overline{\text{ALERT}}$ and $\overline{\text{T_Crit}}$ Open-drain Outputs
- Tachometer Input for Measuring Fan RPM
- 10 bit Plus Sign Remote Diode Temperature Data Format, with 0.125°C Resolution
- SMBus 2.0 Compatible Interface, Supports TIMEOUT
- 5 General Purpose Input/Output pins
- 5 General Purpose Default input pins
- 24-pin WQFN Package

APPLICATIONS

- Computer Processor Thermal Management
- Graphics Processor Thermal Management
- Voltage Regulator Modules
- Electronic Instrumentation
- Power Supplies
- Projectors

KEY SPECIFICATIONS

- Remote Diode Temperature Accuracy (includes quantization error)
 - Ambient Temp
 - 30°C to 50°C
 - 0°C to 85°C
 - Diode Temp
 - 120°C to 140°C
 - 25°C to 140°C
 - Max Error
 - $\pm 1.0^\circ\text{C}$ (max)
 - $\pm 3.0^\circ\text{C}$ (max)
- Local Temp Accuracy (includes quantization error)
 - Ambient Temp 25°C to 125°C
 - Max Error $\pm 3.0^\circ\text{C}$ (max)
- Power Supply Requirements
 - Supply DC Voltage 3.0 V to 3.6 V
 - Supply DC Current 1.1 mA (typ)

DESCRIPTION

The LM64 is a remote diode temperature sensor with PWM fan control. The LM64 accurately measures its own temperature and that of a remote diode. The LM64 remote temperature accuracy is factory trimmed for a MMBT3904 diode-connected transistor with a 16°C offset for high temperatures. $T_{\text{ACTUAL DIODE JUNCTION}} = T_{\text{LM64}} + 16^\circ\text{C}$

The LM64 features a PWM, open-drain, fan control output, 5 GPIO (General Purpose Input/Output) and 5 GPD (General Purpose Default) pins. The 8-step Lookup Table allows for a non-linear fan speed vs. temperature transfer function often used to quiet acoustic fan noise.



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Connection Diagram

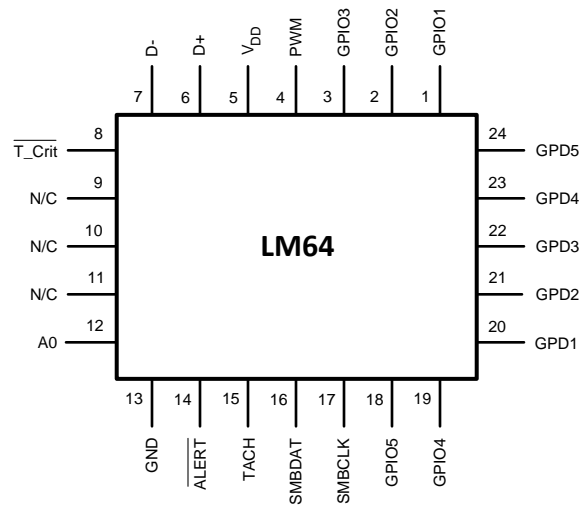


Figure 1. 24-pin WQFN Package

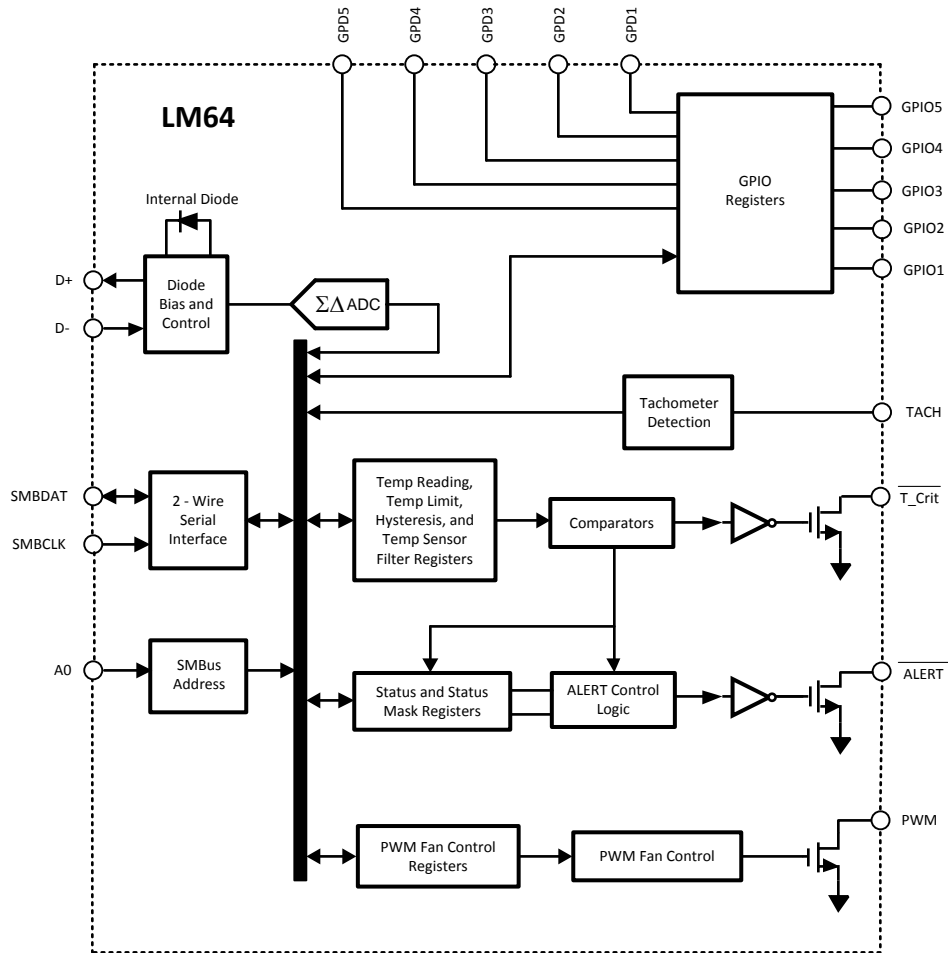
Pin Descriptions

| Pin | Name | Input/Output | Function and Connection |
|-----|-------------------|-------------------------------------|---|
| 1 | GPIO1 | Digital Input/ Open-Drain Output | General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V _{DD} . |
| 2 | GPIO2 | Digital Input/ Open-Drain Output | General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V _{DD} . |
| 3 | GPIO3 | Digital Input/ Open-Drain Output | General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V _{DD} . |
| 4 | PWM | Open-Drain Digital Output | Open-Drain Digital Output. Connect to fan drive circuitry. The power-on default for this pin is low (pin 4 pulled to ground). |
| 5 | V _{DD} | Power Supply Input | Connect to a low-noise +3.3 ± 0.3 VDC power supply, and bypass to GND with a 0.1 μF ceramic capacitor in parallel with a 100 pF ceramic capacitor. A bulk capacitance of 10 μF needs to be in the vicinity of the LM64's V _{DD} pin. |
| 6 | D+ | Analog Input | Connect to the anode (positive side) of the remote diode. A 2.2 nF ceramic capacitor must be connected between pins 6 and 7. |
| 7 | D- | Analog Input | Connect to the cathode (negative side) of the remote diode. A 2.2 nF ceramic capacitor must be connected between pins 6 and 7. |
| 8 | T _{Crit} | Open-Drain Digital Output | Open-Drain Digital Output. Typical pull-up resistor is 3 kΩ to V _{DD} . |
| 9 | N/C | N/A | No Connection. |
| 10 | N/C | N/A | No Connection. |
| 11 | N/C | N/A | No Connection. |
| 12 | A0 | Digital Input | SMBus Address Select pin. If High, the SMBus address is 0x4E or, if Low, the SMBus address is 0x18. Typical pull-up resistor is 10 kΩ to V _{DD} . |
| 13 | GND | Ground | This is the analog and digital ground return. |
| 14 | ALERT | Open-Drain Digital Output | This pin is an open-drain ALERT Output. Typical pull-up resistor is 3 kΩ to V _{DD} . |
| 15 | TACH | Digital Input | This pin is a digital tachometer input. Typical pull-up resistor is 3 kΩ to V _{DD} . |
| 16 | SMBDAT | Digital Input/ Open-Drain Output | This is the bi-directional SMBus data line. Typical pull-up resistor is 1.5 kΩ to V _{DD} . |
| 17 | SMBCLK | Digital Input | This is the SMBus clock input. Typical pull-up resistor is 1.5 kΩ to V _{DD} . |
| 18 | GPIO5 | Digital Input/ Open-Drain Output | General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V _{DD} . |

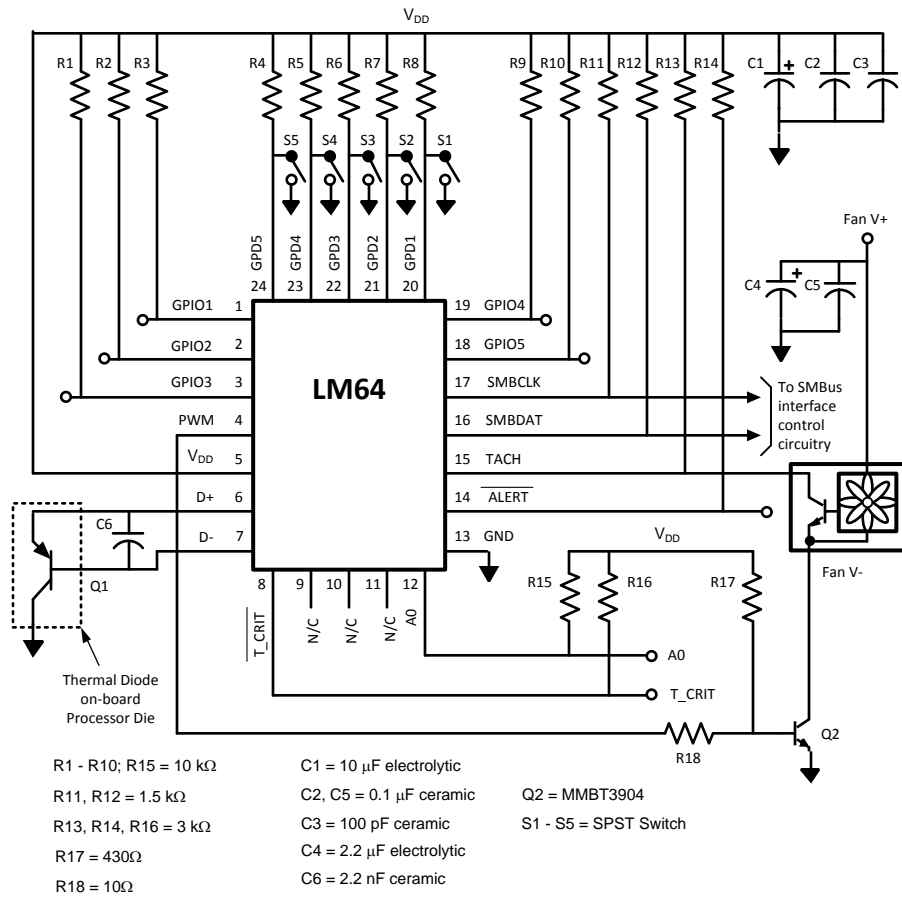
Pin Descriptions (continued)

| Pin | Name | Input/Output | Function and Connection |
|-----|-------|-------------------------------------|--|
| 19 | GPIO4 | Digital Input/ Open-Drain Output | General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V _{DD} . |
| 20 | GPD1 | Digital Input | General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V _{DD} . Always connect to a logical High or Low level. |
| 21 | GPD2 | Digital Input | General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V _{DD} . Always connect to a logical High or Low level. |
| 22 | GPD3 | Digital Input | General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V _{DD} . Always connect to a logical High or Low level. |
| 23 | GPD4 | Digital Input | General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V _{DD} . Always connect to a logical High or Low level. |
| 24 | GPD5 | Digital Input | General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V _{DD} . Always connect to a logical High or Low level. |

Simplified Block Diagram



Typical Application



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾⁽³⁾

| | | |
|--|-------------------------------|--------|
| Supply Voltage, V_{DD} | -0.3 V to 6.0 V | |
| Voltage on SMBDAT, SMBCLK, \overline{ALERT} , $\overline{T_Crit}$, PWM Pins | -0.5 V to 6.0 V | |
| Voltage on Other Pins | -0.3 V to ($V_{DD} + 0.3$ V) | |
| Input Current, D- Pin | ± 1 mA | |
| Input Current at All Other Pins ⁽⁴⁾ | 5 mA | |
| Package Input Current ⁽⁴⁾ | 30 mA | |
| Package Power Dissipation SMBDAT, \overline{ALERT} , $\overline{T_Crit}$, PWM pins | See ⁽⁵⁾ | |
| Output Sink Current | 10 mA | |
| Storage Temperature | -65°C to +150°C | |
| ESD Susceptibility ⁽⁶⁾ | Human Body Model | 2000 V |
| | Machine Model | 200 V |
| SMT Soldering Information See AN-1187 (SNOA401Q), "Leadless Leadframe Package" for information on SMT Assembly using LLP Packages. | | |

- (1) All voltages are measured with respect to GND, unless otherwise noted.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) When the input voltage (V_{IN}) at any pin exceeds the power supplies ($V_{IN} < GND$ or $V_{IN} > V+$), the current at that pin should be limited to 5 mA. Parasitic components and/or ESD protection circuitry are shown in the [Table 1](#), for the LM64's pins, by an "X" when it exists. Care should be taken not to forward bias the parasitic diode, D1, present on pins D+ and D-. Doing so by more than 50 mV may corrupt temperature measurements.
- (5) See AN-1187 [SNOA401](#) for Thermal Resistance Junction-to-Ambient Temperature.
- (6) Human body model, 100 pF discharged through a 1.5 k Ω resistor. Machine model, 200 pF discharged directly into each pin. See [Figure 3](#) for the ESD Protection Input Structure.

Operating Ratings⁽¹⁾⁽²⁾

| | |
|-----------------------------------|---|
| LM64 Operating Temperature Range | $0^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ |
| Remote Diode Temperature Range | $25^{\circ}\text{C} \leq T_D \leq +140^{\circ}\text{C}$ |
| Electrical Characteristics | $T_{MIN} \leq T_A \leq T_{MAX}$ |
| Supply Voltage Range (V_{DD}) | +3.0 V to +3.6 V |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) All voltages are measured with respect to GND, unless otherwise noted.

DC Electrical Characteristics

TEMPERATURE-TO-DIGITAL CONVERTER CHARACTERISTICS

The following specifications apply for $V_{DD} = 3.0$ VDC to 3.6 VDC, and all analog source impedance $R_S = 50 \Omega$ unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = +25^\circ\text{C}$.

| Parameter | Conditions | | Typical (1) | Limits (2) | Units (Limits) |
|---|--|--|----------------|---------------------------|------------------------|
| Temperature Error using a diode-connected MMBT3904 transistor. T_D is the Remote Diode Junction Temperature. $T_D = T_{LM64} + 16^\circ\text{C}$ | $T_A = +30^\circ\text{C}$ to $+50^\circ\text{C}$ | $T_D = +120^\circ\text{C}$ to $+140^\circ\text{C}$ | | ± 1 | $^\circ\text{C}$ (max) |
| | $T_A = +0^\circ\text{C}$ to $+85^\circ\text{C}$ | $T_D = +25^\circ\text{C}$ to $+140^\circ\text{C}$ | | ± 3 | $^\circ\text{C}$ (max) |
| Temperature Error Using the Local Diode | $T_A = +25^\circ\text{C}$ to $+125^\circ\text{C}$ ⁽³⁾ | | ± 1 | ± 3 | $^\circ\text{C}$ (max) |
| Remote Diode Resolution | | | 11 | | Bits |
| | | | 0.125 | | $^\circ\text{C}$ |
| Local Diode Resolution | | | 8 | | Bits |
| | | | 1 | | $^\circ\text{C}$ |
| Conversion Time of All Temperatures | Fastest Setting | | 31.25 | 34.4 | ms (max) |
| D- Source Voltage | | | 0.7 | | V |
| Diode Source Current | $(V_{D+} - V_{D-}) = +0.65$ V; High Current | | 160 | 315 | μA (max) |
| | | | | 110 | μA (min) |
| | Low Current | | 13 | 20 | μA (max) |
| | | | 7 | μA (min) | |

- (1) "Typicals" are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
- (2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
- (3) Local temperature accuracy does not include the effects of self-heating. The rise in temperature due to self-heating is the product of the internal power dissipation of the LM64 and the thermal resistance. See AN-1187 (SNOA401) for the thermal resistance to be used in the self-heating calculation.

Operating Electrical Characteristics

| Parameter | Conditions | | Typ (1) | Limits (2) | Units |
|--|--|------|------------|---------------|---------------|
| $\overline{\text{ALERT}}$, $\overline{T_Crit}$ and PWM Output Saturation Voltage | $\overline{\text{ALERT}}$, $\overline{T_Crit}$ | PWM | | | |
| | I_{OUT} | 4 mA | 6 mA | 0.4 | V (max) |
| | I_{OUT} | 6 mA | | 0.55 | |
| Power-On-Reset Threshold Voltage | | | | 2.4 | V (max) |
| | | | | 1.8 | V (min) |
| Supply Current ⁽³⁾ | SMBus Inactive, 16 Hz Conversion Rate | | 1.1 | 2.0 | mA (max) |
| | STANDBY Mode | | 320 | | μA |

- (1) "Typicals" are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
- (2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
- (3) The supply current will not increase substantially with an SMBus transaction.

AC Electrical Characteristics

The following specifications apply for $V_{DD} = 3.0$ VDC to 3.6 VDC, and all analog source impedance $R_S = 50\Omega$ unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = +25^\circ\text{C}$.

| Symbol | Parameter | Conditions | Typical (1) | Limits (2) | Units (Limit) |
|----------------------------|-----------------------------|------------|----------------|---------------|------------------|
| TACHOMETER ACCURACY | | | | | |
| | Fan Control Accuracy | | | ± 10 | % (max) |
| | Fan Full-Scale Count | | | 65535 | (max) |
| | Fan Counter Clock Frequency | | 90 | | kHz |
| | Fan Count Update Frequency | | 1.0 | | Hz |
| FAN PWM OUTPUT | | | | | |
| | Frequency Accuracy | | | ± 10 | % (max) |

- (1) "Typicals" are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
- (2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

Digital Electrical Characteristics

| Symbol | Parameter | Conditions | Typical (1) | Limits (2) | Units (Limit) |
|----------|----------------------------|-----------------------|----------------|---------------|---------------------|
| V_{IH} | Logical High Input Voltage | | | 2.1 | V (min) |
| V_{IL} | Logical Low Input Voltage | | | 0.8 | V (max) |
| I_{IH} | Logical High Input Current | $V_{IN} = V_{DD}$ | 0.005 | +10 | μA (max) |
| I_{IL} | Logical Low Input Current | $V_{IN} = \text{GND}$ | -0.005 | -10 | μA (max) |
| C_{IN} | Digital Input Capacitance | | 20 | | pF |

- (1) "Typicals" are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
- (2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

SMBus Logical Electrical Characteristics

The following specifications apply for $V_{DD} = 3.0$ VDC to 3.6 VDC, and all analog source impedance $R_S = 50\Omega$ unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = +25^\circ\text{C}$.

| Symbol | Parameter | Conditions | Typical (1) | Limits (2) | Units (Limit) |
|---------------------------------|--------------------------------|------------------------|----------------|---------------|---------------------|
| SMBDAT OPEN-DRAIN OUTPUT | | | | | |
| V_{OL} | Logic Low Level Output Voltage | $I_{OL} = 4\text{ mA}$ | | 0.4 | V (max) |
| I_{OH} | High Level Output Current | $V_{OUT} = V_{DD}$ | 0.03 | 10 | μA (max) |
| SMBDAT, SMBCLK INPUTS | | | | | |
| V_{IH} | Logical High Input Voltage | | | 2.1 | V (min) |
| V_{IL} | Logical Low Input Voltage | | | 0.8 | V (max) |
| V_{HYST} | Logic Input Hysteresis Voltage | | 400 | | mV |

- (1) "Typicals" are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
- (2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

SMBus Digital Switching Characteristics

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0$ VDC to $+3.6$ VDC, C_L (load capacitance) on output lines = 80 pF. **Boldface limits apply for $T_A = T_J$; $T_{MIN} \leq T_A \leq T_{MAX}$** ; all other limits $T_A = T_J = +25^\circ\text{C}$, unless otherwise noted. The switching characteristics of the LM64 fully meet or exceed the published specifications of the SMBus version 2.0. The following parameters are the timing relationships between SMBCLK and SMBDAT signals related to the LM64. They adhere to but are not necessarily the same as the SMBus bus specifications.

| Symbol | Parameter | Conditions | Limits (1) | Units (Limit) |
|---------------|---|---|--------------------------|--|
| f_{SMB} | SMBus Clock Frequency | | 10 100 | kHz (min) kHz (max) |
| t_{LOW} | SMBus Clock Low Time | From $V_{IN(0) \max}$ to $V_{IN(0) \max}$ | 4.7 | μs (min) |
| t_{HIGH} | SMBus Clock High Time | From $V_{IN(1) \min}$ to $V_{IN(1) \min}$ | 4.0 50 | μs (min) μs (max) |
| t_R | SMBus Rise Time | See (2) | 1 | μs (max) |
| t_F | SMBus Fall Time | See (3) | 0.3 | μs (max) |
| t_{OF} | Output Fall Time | $C_L = 400$ pF, $I_O = 3$ mA | 250 | ns (max) |
| $t_{TIMEOUT}$ | SMBData and SMBCLK Time Low for Reset of Serial Interface See (4) | | 25 35 | ms (min) ms (max) |
| $t_{SU:DAT}$ | Data In Setup Time to SMBCLK High | | 250 | ns (min) |
| $t_{HD:DAT}$ | Data Out Hold Time after SMBCLK Low | | 300 930 | ns (min) ns (max) |
| $t_{HD:STA}$ | Hold Time after (Repeated) Start Condition. After this period the first clock is generated. | | 4.0 | μs (min) |
| $t_{SU:STO}$ | Stop Condition SMBCLK High to SMBDAT Low (Stop Condition Setup) | | 100 | ns (min) |
| $t_{SU:STA}$ | SMBus Repeated Start-Condition Setup Time, SMBCLK High to SMBDAT Low | | 4.7 | μs (min) |
| t_{BUF} | SMBus Free Time between Stop and Start Conditions | | 4.7 | μs (min) |

(1) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

(2) The output rise time is measured from ($V_{IL \max} - 0.15$ V) to ($V_{IH \min} + 0.15$ V).

(3) The output fall time is measured from ($V_{IH \min} + 0.15$ V) to ($V_{IL \min} - 0.15$ V).

(4) Holding the SMBData and/or SMBCLK lines Low for a time interval greater than $t_{TIMEOUT}$ will reset the LM64's SMBus state machine, therefore setting SMBDAT and SMBCLK pins to a high impedance state.

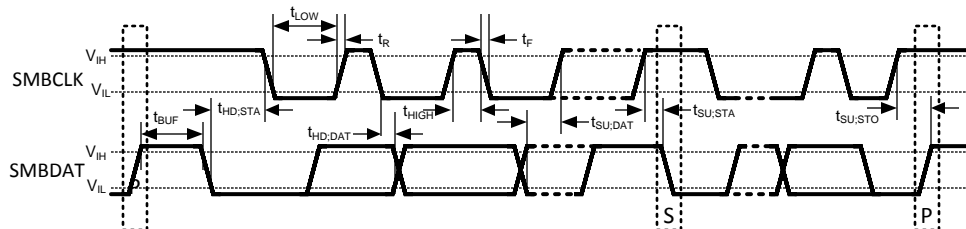


Figure 2. SMBus Timing Diagram for SMBCLK and SMBDAT Signals

Table 1.

| Pin Name | Pin # | D1 | D2 | D3 | D4 | D5 | D6 | R1 | SNP | ESD CLAMP |
|-------------------|-------|----|----|----|----|----|----|----|-----|-----------|
| GPIO1 | 1 | | | | | | X | X | X | |
| GPIO2 | 2 | | | | | | X | X | X | |
| GPIO3 | 3 | | | | | | X | X | X | |
| PWM | 4 | | | | | | X | X | X | |
| V _{DD} | 5 | | | | | | | | | X |
| D+ | 6 | X | X | | | X | X | X | | X |
| D- | 7 | X | X | | X | X | X | | | X |
| T _{Crit} | 8 | | X | | | | X | X | X | |
| A0 | 12 | | | | | | | | X | |
| ALERT | 14 | | X | | | | X | X | X | |
| TACH | 15 | | | | | | X | X | X | |
| SMBDAT | 16 | | | | | | X | X | X | |
| SMBCLK | 17 | | | | | | | | X | |
| GPIO5 | 18 | | | | | | X | X | X | |
| GPIO4 | 19 | | | | | | X | X | X | |
| GPD1 | 20 | | | | | | | | X | |
| GPD2 | 21 | | | | | | | | X | |
| GPD3 | 22 | | | | | | | | X | |
| GPD4 | 23 | | | | | | | | X | |
| GPD5 | 24 | | | | | | | | X | |

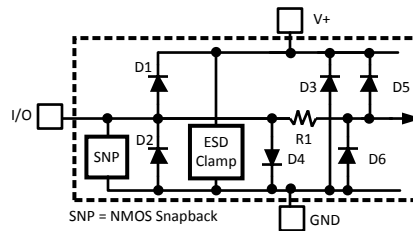


Figure 3. ESD Protection Input Structure

FUNCTIONAL DESCRIPTION

The LM64 Remote Diode Temperature Sensor with Integrated Fan Control incorporates a ΔV_{BE} -based temperature sensor using a Local or Remote diode and a 10-bit plus sign $\Delta\Sigma$ ADC (Delta-Sigma Analog-to-Digital Converter). The pulse-width modulated (PWM) open-drain output, with a pull-up resistor, can drive a switching transistor to modulate the fan. The LM64 can measure the fan speed on the pulses from the fan's open-collector tachometer output, pulled up by a 1.5 k Ω resistor to V_{DD} . The ALERT open-drain output will be pulled low under certain conditions described in the sections below. The T_Crit open-drain output will be pulled low when the T_Crit setpoint temperature limit is exceeded. This behaves as a typical comparator function without any latching.

The LM64's two-wire interface is compatible with the SMBus Specification 2.0 . For more information the reader is directed to www.smbus.org.

In the LM64, digital comparators are used to compare the measured Local Temperature (LT) to the Local High Setpoint user-programmable temperature limit register. The measured Remote Temperature (RT) is digitally compared to the Remote High Setpoint (RHS), the Remote Low Setpoint (RLS), and the Remote T_CRIT Setpoint (RCS) user-programmable temperature limits. An ALERT output will occur when the measured temperature is: (1) higher than either the High Setpoint or the T_CRIT Setpoint, or (2) lower than the Low Setpoint. The ALERT Mask register allows the user to prevent the generation of these ALERT outputs.

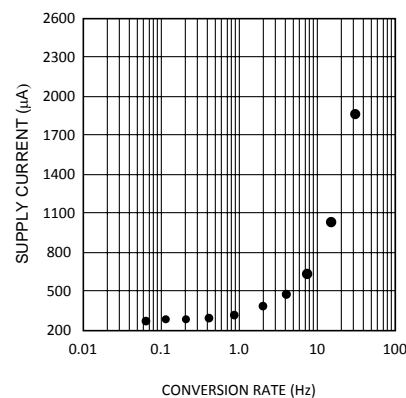
The temperature hysteresis is set by the value placed in the Hysteresis Register (TH).

The LM64 may be placed in a low power Standby mode by setting the Standby bit found in the Configuration Register. In the Standby mode continuous conversions are stopped. In Standby mode the user may choose to allow the PWM output signal to continue, or not, by programming the PWM Disable in Standby bit in the Configuration Register.

The Local Temperature reading and setpoint data registers are 8-bits wide. The format of the 11-bit remote temperature data is a 16-bit left justified word. Two 8-bit registers, high and low bytes, are provided for each setpoint as well as the temperature reading. Two Remote Temperature Offset (RTO) Registers: High Byte and Low Byte (RTOHB and RTOLB) may be used to correct the temperature readings by adding or subtracting a fixed value based on a different non-ideality factor of the thermal diode if different from the graphics processor thermal diode. See [Diode Non_Ideality](#).

CONVERSION SEQUENCE

The LM64 takes approximately 31.25 ms to convert the Local Temperature (LT), Remote Temperature (RT), and to update all of its registers. The Conversion Rate may be modified using the Conversion Rate Register. When the conversion rate is modified a delay is inserted between conversions, the actual conversion time remains at 31.25 ms. Different Conversion Rates will cause the LM64 to draw different amounts of supply current as shown in [Figure 4](#).



THE ALERT OUTPUT

When the ALERT Mask bit in the Configuration register is written as zero the ALERT interrupts are enabled.

The LM64's $\overline{\text{ALERT}}$ pin is versatile and can produce three different methods of use to best serve the system designer: (1) as a temperature comparator (2) as a temperature-based interrupt flag, and (3) as part of an SMBus ALERT System. The three methods of use are further described below. The ALERT and interrupt methods are different only in how the user interacts with the LM64.

The remote temperature (RT) reading is associated with a T_CRIT Setpoint Register, and both local and remote temperature (LT and RT) readings are associated with a HIGH setpoint register (LHS and RHS). The RT is also associated with a LOW setpoint register (RLS). At the end of every temperature reading a digital comparison determines whether that reading is above its HIGH or T_CRIT setpoint or below its LOW setpoint. If so, the corresponding bit in the ALERT Status Register is set. If the ALERT mask bit is low, any bit set in the ALERT Status Register, with the exception of Busy or Open, will cause the $\overline{\text{ALERT}}$ output to be pulled low. Any temperature conversion that is out of the limits defined in the temperature setpoint registers will trigger an ALERT. Additionally, the ALERT Mask Bit must be cleared to trigger an ALERT in all modes.

The three different ALERT modes will be discussed in the following sections.

$\overline{\text{ALERT}}$ Output as a Temperature Comparator

When the LM64 is used in a system in which does not require temperature-based interrupts, the $\overline{\text{ALERT}}$ output could be used as a temperature comparator. In this mode, once the condition that triggered the $\overline{\text{ALERT}}$ to go low is no longer present, the $\overline{\text{ALERT}}$ is negated (Figure 5). For example, if the $\overline{\text{ALERT}}$ output was activated by the comparison of $\text{LT} > \text{LHS}$, when this condition is no longer true, the $\overline{\text{ALERT}}$ will return HIGH. This mode allows operation without software intervention, once all registers are configured during set-up. In order for the $\overline{\text{ALERT}}$ to be used as a temperature comparator, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be asserted. This is not the power-on default state.

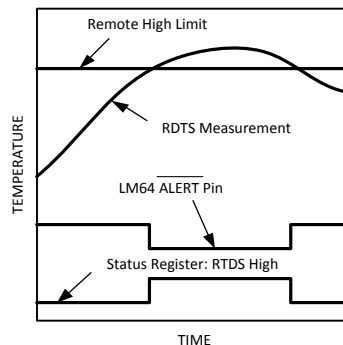


Figure 5. $\overline{\text{ALERT}}$ Output as Temperature Comparator Response Diagram

$\overline{\text{ALERT}}$ Output as an Interrupt

The LM64's $\overline{\text{ALERT}}$ output can be implemented as a simple interrupt signal when it is used to trigger an interrupt service routine. In such systems it is desirable for the interrupt flag to repeatedly trigger during or before the interrupt service routine has been completed. Under this method of operation, during the read of the ALERT Status Register the LM64 will set the ALERT Mask bit in the Configuration Register if any bit in the ALERT Status Register is set, with the exception of Busy and Open. This prevents further ALERT triggering until the master has reset the ALERT Mask bit, at the end of the interrupt service routine. The ALERT Status Register bits are cleared only upon a read command from the master (see Figure 5) and will be re-asserted at the end of the next conversion if the triggering condition(s) persist(s). In order for the $\overline{\text{ALERT}}$ to be used as a dedicated interrupt signal, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low. This is the power-on default state. The following sequence describes the response of a system that uses the ALERT output pin as an interrupt flag:

1. Master senses $\overline{\text{ALERT}}$ low.
2. Master reads the LM64 ALERT Status Register to determine what caused the ALERT.
3. LM64 clears ALERT Status Register, resets the $\overline{\text{ALERT}}$ HIGH and sets the ALERT Mask bit in the

Configuration Register.

4. Master attends to conditions that caused the $\overline{\text{ALERT}}$ to be triggered. The fan is started, setpoint limits are adjusted, etc.
5. Master resets the ALERT Mask bit in the Configuration Register.

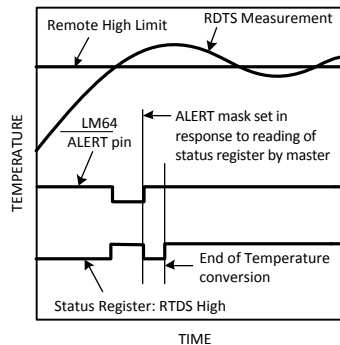


Figure 6. $\overline{\text{ALERT}}$ Output as an Interrupt Temperature Response Diagram

$\overline{\text{ALERT}}$ Output as an SMBus ALERT

An SMBus alert line is created when the $\overline{\text{ALERT}}$ output is connected to: (1) one or more $\overline{\text{ALERT}}$ outputs of other SMBus compatible devices, and (2) to a master. Under this implementation, the LM64's ALERT should be operated using the ARA (Alert Response Address) protocol. The SMBus 2.0 ARA protocol, defined in the SMBus specification 2.0, is a procedure designed to assist the master in determining which part generated an interrupt and to service that interrupt.

The SMBus alert line is connected to the open-drain ports of all devices on the bus, thereby AND'ing them together. The ARA method allows the SMBus master, with one command, to identify which part is pulling the SMBus alert line LOW. It also prevents the part from pulling the line LOW again for the same triggering condition. When an ARA command is received by all devices on the bus, the devices pulling the SMBus alert line LOW: (1) send their address to the master and (2) release the SMBus alert line after acknowledgement of their address.

The SMBus Specifications 1.1 and 2.0 state that in response to an ARA (Alert Response Address) "after acknowledging the slave address the device must disengage its ALERT pulldown". Furthermore, "if the host still sees ALERT low when the message transfer is complete, it knows to read the ARA again." This SMBus "disengaging ALERT requirement prevents locking up the SMBus alert line. Competitive parts may address the "disengaging of ALERT" differently than the LM64 or not at all. SMBus systems that implement the ARA protocol as suggested for the LM64 will be fully compatible with all competitive parts.

The LM64 fulfills "disengaging of ALERT" by setting the ALERT Mask Bit in the Configuration Register after sending out its address in response to an ARA and releasing the $\overline{\text{ALERT}}$ output pin. Once the ALERT Mask bit is activated, the ALERT output pin will be disabled until enabled by software. In order to enable the ALERT the master must read the ALERT Status Register, during the interrupt service routine and then reset the ALERT Mask bit in the Configuration Register to 0 at the end of the interrupt service routine.

The following sequence describes the ARA response protocol.

1. Master senses SMBus alert line low
2. Master sends a START followed by the Alert Response Address (ARA) with a Read Command.
3. Alerting Device(s) send ACK.
4. Alerting Device(s) send their address. While transmitting their address, alerting devices sense whether their address has been transmitted correctly. (The LM64 will reset its $\overline{\text{ALERT}}$ output and set the ALERT Mask bit once its complete address has been transmitted successfully.)
5. Master/slave NoACK
6. Master sends STOP
7. Master attends to conditions that caused the ALERT to be triggered. The ALERT Status Register is read and fan started, setpoints adjusted, etc.

8. Master resets the ALERT Mask bit in the Configuration Register.

The ARA, 000 1100, is a general call address. No device should ever be assigned to this address.

The ALERT Configuration bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low in order for the LM64 to respond to the ARA command.

The $\overline{\text{ALERT}}$ output can be disabled by setting the ALERT Mask bit in the Configuration Register. The power-on default is to have the ALERT Mask bit and the ALERT Configuration bit low.

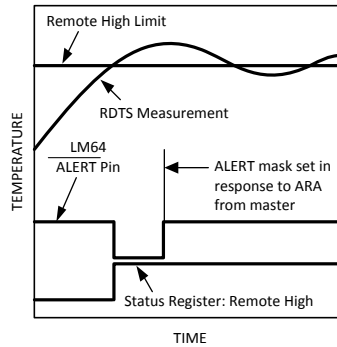


Figure 7. $\overline{\text{ALERT}}$ Output as an SMBus ALERT Temperature Response Diagram

SMBus INTERFACE

Since the LM64 operates as a slave on the SMBus, the SMBCLK line is an input and the SMBDAT line is bi-directional. The LM64 never drives the SMBCLK line and it does not support clock stretching. The LM64 has two hardware-selectable 7-bit slave addresses. The user may input a logical High or Low on the A0 Address pin to select one of the two pre-programmed SMBus slave addresses. The options are as follows:

| A0 Pin | SMBus Address 0x[Hex] | SMBus Slave Address Bits | | | | | | |
|--------|-----------------------|--------------------------|----|----|----|----|----|----|
| | | A6 | A5 | A4 | A3 | A2 | A1 | A0 |
| 0 | 18 | 0 | 0 | 1 | 1 | 0 | 0 | 0 |
| 1 | 4E | 1 | 0 | 0 | 1 | 1 | 1 | 0 |

POWER-ON RESET (POR) DEFAULT STATES

For information on the POR default states see [LM64 REGISTER MAP IN FUNCTIONAL ORDER](#).

TEMPERATURE DATA FORMAT

Temperature data can only be read from the Local and Remote Temperature registers. The High, Low and T_CRIT setpoint registers are Read/Write.

Remote temperature data is represented by an 11-bit, two's complement word with a Least Significant Bit (LSB) equal to 0.125°C. The data format is a left justified 16-bit word available in two 8-bit registers. Some examples of temperature conversions are shown below.

Table 2. Actual vs. LM64 Remote Temperature Conversion⁽¹⁾

| Actual Remote Diode Temperature, °C | LM64 Remote Diode Temperature Register, °C | Binary Results in LM64 Remote Temperature Register | Hex Remote Temperature Register |
|-------------------------------------|--|--|---------------------------------|
| 120 | +104 | 0110 1000 0000 0000 | 6800h |
| 125 | +109 | 0110 1101 0000 0000 | 6D00h |
| 126 | +110 | 0110 1110 0000 0000 | 6E00h |
| 130 | +114 | 0111 0010 0010 0000 | 7200h |
| 135 | +119 | 0111 0111 0000 0000 | 7700h |
| 140 | +124 | 0111 1100 0000 0000 | 7C00h |

(1) Output is 11-bit two's complement word. LSB = 0.125 °C.

Table 3. Actual vs. Remote T_Crit Setpoint Example

| Actual Remote Diode T_Crit Setpoint, °C | Remote T_CRIT High Setpoint, °C | Binary Remote T_CRIT High Setpoint Value | Hex Remote T_CRIT High Setpoint Value |
|---|---------------------------------|--|---------------------------------------|
| 126 | +110 | 0110 1110 | 6Eh |

Local Temperature data is represented by an 8-bit, two's complement byte with an LSB equal to 1°C:

| Temperature | Digital Output | |
|-------------|----------------|-----|
| | Binary | Hex |
| +125°C | 0111 1101 | 7D |
| +25°C | 0001 1001 | 19 |
| +1°C | 0000 0001 | 01 |
| 0°C | 0000 0000 | 00 |
| -1°C | 1111 1111 | FF |
| -25°C | 1110 0111 | E7 |
| -55°C | 1100 1001 | C9 |

OPEN-DRAIN OUTPUTS, INPUTS, AND PULL-UP RESISTORS

The SMBDAT, $\overline{\text{ALERT}}$, $\overline{\text{T_Crit}}$, GPIO and PWM open-drain outputs and the GPD, TACH, and A0 inputs are pulled-up by pull-up resistors to V_{DD} as suggested in the table below.

| Pin Name | Pin Number | Suggested Pull-up Resistor | |
|----------|------------|----------------------------|--------------------|
| | | Range | Typical |
| SMBCLK | 17 | 1 kΩ to 2 kΩ | 1.5 kΩ |
| SMBDAT | 16 | 1 kΩ to 2 kΩ | 1.5 kΩ |
| ALERT | 14 | 1 kΩ to 5 kΩ | 3 kΩ |
| T_Crit | 8 | 1 kΩ to 5 kΩ | 3 kΩ |
| A0 | 12 | 5 kΩ to 20 kΩ | 10 kΩ |
| GPIOx | 1-3;18,19 | 5 kΩ to 20 kΩ | 10 kΩ |
| GPDx | 20-24 | 5 kΩ to 20 kΩ | 10 kΩ |
| PWM | 4 | See ⁽¹⁾ | See ⁽¹⁾ |
| TACH | 15 | 1 kΩ to 5 kΩ | 3 kΩ |

(1) Depends on the fan drive circuitry connected to this pin. In the absence of fan control circuitry use a 1 kΩ pull-up resistor to V_{DD} .

DIODE FAULT DETECTION

The LM64 can detect fault conditions caused by the remote diode. If the D+ pin is detected to be shorted to V_{DD} , or open: (1) the Remote Temperature High Byte (RTHB) register is loaded with 127°C, (2) the Remote Temperature Low Byte (RTLB) register is loaded with 0, and (3) the OPEN bit (D2) in the status register is set. Therefore, if the Remote T_CRIT setpoint register (RCS): (1) is set to a value less than +127°C and (2) the ALERT Mask is disabled, then the $\overline{\text{ALERT}}$ output pin will be pulled low. If the Remote High Setpoint High Byte (RHS HB) is set to a value less than +127°C and (2) the ALERT Mask is disabled, then the $\overline{\text{ALERT}}$ and $\overline{\text{T_Crit}}$ outputs will be pulled low. The OPEN bit by itself will not trigger an ALERT.

If the D+ pin is shorted to either ground or D-, then the Remote Temperature High Byte (RTHB) register is loaded with -128°C (1000 0000) and the OPEN bit in the ALERT Status Register will not be set. A temperature reading of -128°C indicates that D+ is shorted to either ground or D-. If the value in the Remote Low Setpoint High Byte (RLSHB) Register is more than -128°C and the ALERT Mask is Disabled, $\overline{\text{ALERT}}$ will be pulled low.

COMMUNICATING WITH THE LM64

Each data register in the LM64 falls into one of four types of user accessibility:

1. Read Only
2. Write Only
3. Read/Write same address
4. Read/Write different address

A Write to the LM64 is comprised of an address byte and a command byte. A write to any register requires one data byte.

Reading the LM64 Registers can take place after the requisite register setup sequence takes place. See [LM64 Required Initial Fan Control Register Sequence](#).

The data byte has the Most Significant Bit (MSB) first. At the end of a read, the LM64 can accept either Acknowledge or No-Acknowledge from the Master. Note that the No-Acknowledge is typically used as a signal for the slave indicating that the Master has read its last byte.

DIGITAL FILTER

The LM64 incorporates a user-configured digital filter to suppress erroneous Remote Temperature readings due to noise. The filter is accessed in the Remote Diode Temperature Filter and Comparator Mode Register. The filter can be set according to the following table.

Level 2 is maximum filtering.

Table 4. Digital Filter Selection Table

| D2 | D1 | Filter |
|----|----|-----------|
| 0 | 0 | No Filter |
| 0 | 1 | Level 1 |
| 1 | 0 | Level 1 |
| 1 | 1 | Level 2 |

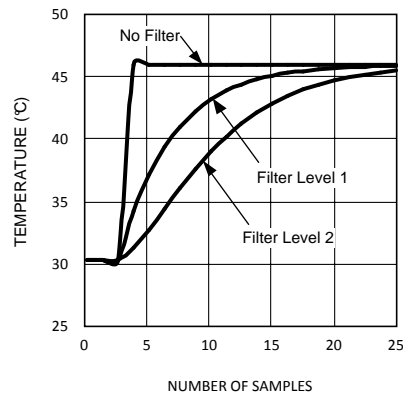


Figure 8. Step Response of the Digital Filter

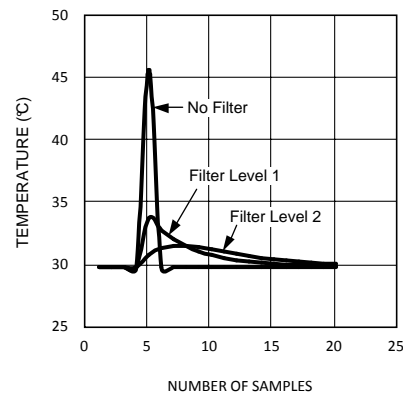
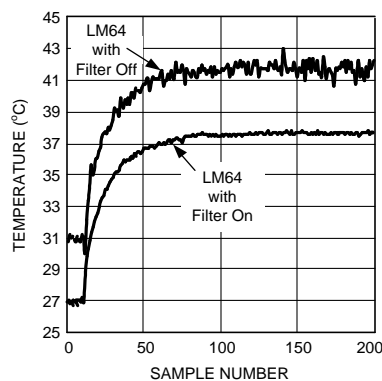


Figure 9. Impulse Response of the Digital Filter



The Filter on and off curves were purposely offset to better show noise performance.

Figure 10. Digital Filter Response in an Intel Pentium 4 processor System

FAULT QUEUE

The LM64 incorporates a Fault Queue to suppress erroneous ALERT triggering. The Fault Queue prevents false triggering by requiring three consecutive out-of-limit HIGH, LOW, or T_CRIT temperature readings. See [Figure 11](#). The Fault Queue defaults to OFF upon power-up and may be activated by setting the RDTs Fault Queue bit in the Configuration Register to a 1.

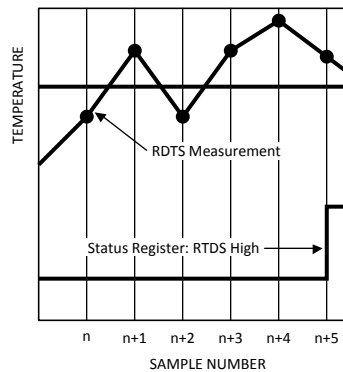


Figure 11. Fault Queue Temperature Response Diagram

ONE-SHOT REGISTER

The One-Shot Register is used to initiate a single conversion and comparison cycle when the device is in standby mode, after which the data returns to standby. This is not a data register. A write operation causes the one-shot conversion. The data written to this address is irrelevant and is not stored. A zero will always be read from this register.

SERIAL INTERFACE RESET

In the event that the SMBus Master is reset while the LM64 is transmitting on the SMBDAT line, the LM64 must be returned to a known state in the communication protocol. This may be done in one of two ways:

1. When SMBDAT is Low, the LM64 SMBus state machine resets to the SMBus idle state if either SMBData or SMBCLK are held Low for more than 35 ms (t_{TIMEOUT}). All devices are to timeout when either the SMBCLK or SMBDAT lines are held Low for 25 ms – 35 ms. Therefore, to insure a timeout of all devices on the bus, either the SMBCLK or the SMBData line must be held Low for at least 35 ms.
2. With both SMBDAT and SMBCLK High, the master can initiate an SMBus start condition with a High to Low transition on the SMBDAT line. The LM64 will respond properly to an SMBus start condition at any point during the communication. After the start the LM64 will expect an SMBus Address address byte.

LM64 Registers

The following pages include: [LM64 REGISTER MAP IN HEXADECIMAL ORDER](#) a Register Map in Hexadecimal Order, which shows a summary of all registers and their bit assignments, [LM64 REGISTER MAP IN FUNCTIONAL ORDER](#), a Register Map in Functional Order, and [LM64 INITIAL REGISTER SEQUENCE AND REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER](#), a detailed explanation of each register. Do not address the unused or manufacturer's test registers.

LM64 REGISTER MAP IN HEXADECIMAL ORDER

The following is a Register Map grouped in hexadecimal address order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of “Same As” address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

| Register 0x[HEX] | Register Name | DATA BITS | | | | | | | |
|---------------------|-----------------------|---|---------|---------|---------|---------|---------|---------|---------|
| | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 00 | Local Temperature | LT7 | LT6 | LT5 | LT4 | LT3 | LT2 | LT1 | LT0 |
| 01 | Rmt Temp MSB | RTHB± | RTHB14 | RTHB13 | RTHB12 | RTHB11 | RTHB10 | RTHB9 | RTHB8 |
| 02 | ALERT Status | BUSY | LHIGH | 0 | RHIGH | RLOW | RDFA | RCRIT | TACH |
| 03 | Configuration | ALTMSK | STBY | PWMDIS | 0 | 0 | ALT/TCH | TCRITOV | FLTQUE |
| 04 | Conversion Rate | 0 | 0 | 0 | 0 | CONV3 | CONV2 | CONV1 | CONV0 |
| 05 | Local High Setpoint | LHS7 | LHS6 | LHS5 | LHS4 | LHS3 | LHS2 | LHS1 | LHS0 |
| 06 | [Reserved] | Not Used | | | | | | | |
| 07 | Rmt High Setpoint MSB | RHSHB15 | RHSHB14 | RHHBS13 | RHSHB12 | RHSHB11 | RHSHB10 | RHSHB9 | RHSHB8 |
| 08 | Rmt Low Setpoint MSB | RLSHB15 | RLSHB14 | RLSHB13 | RLSHB12 | RLHBS11 | RLSHB10 | RLSHB9 | RLSHB8 |
| (09) | Same as 03 | | | | | | | | |
| (0A) | Same as 04 | | | | | | | | |
| (0B) | Same as 05 | | | | | | | | |
| 0C | [Reserved] | Not Used | | | | | | | |
| (0D) | Same as 07 | | | | | | | | |
| (0E) | Same as 08 | | | | | | | | |
| 0F | One Shot | Write Only. Write command triggers one temperature conversion cycle. | | | | | | | |
| 10 | Rmt Temp LSB | RTL7 | RTL6 | RTL5 | 0 | 0 | 0 | 0 | 0 |
| 11 | Rmt Temp Offset MSB | RTOHB15 | RTOHB14 | RTOHB13 | RTOHB12 | RTOHB11 | RTOHB10 | RTOHB9 | RTOHB8 |
| 12 | Rmt Temp Offset LSB | RTOLB7 | RTOLB6 | RTOLB5 | 0 | 0 | 0 | 0 | 0 |
| 13 | Rmt High Setpoint LSB | RHSLB7 | RHSLB6 | RHSLB5 | 0 | 0 | 0 | 0 | 0 |
| 14 | Rmt Low Setpoint LSB | RLSLB7 | RLSLB6 | RLSLB5 | 0 | 0 | 0 | 0 | 0 |
| 15 | [Reserved] | Not Used | | | | | | | |
| 16 | ALERT Mask | 1 | ALTMSK6 | 1 | ALTMSK4 | ALTMSK3 | 1 | ALTMSK1 | ALTMSK0 |
| 17 | [Reserved] | Not Used | | | | | | | |
| 18 | [Reserved] | Not Used | | | | | | | |
| 19 | Rmt TCRIT Setpoint | RCS7 | RCS6 | RCS5 | RCS4 | RCS3 | RCS2 | RCS1 | RCS0 |
| 1A | General Purpose Input | 0 | 0 | 0 | GPI5 | GPI4 | GPI3 | GPI2 | GPI1 |

| Register 0x[HEX] | Register Name | DATA BITS | | | | | | | |
|---------------------|-------------------------|--|--------|--------|---------|---------|---------|----------|----------|
| | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 1B | General Purpose Output | 0 | 0 | 0 | GPO5 | GPO4 | GPO3 | GPO2 | GPO1 |
| 1C–1F | [Reserved] | Not Used | | | | | | | |
| 20 | [Reserved] | Not Used | | | | | | | |
| 21 | Rmt TCRIH Hysteresis | RTH7 | RTH6 | RTH5 | RTH4 | RTH3 | RTH2 | RTH1 | RTH0 |
| 22–2F | [Reserved] | Not Used | | | | | | | |
| 30–3F | [Reserved] | Not Used | | | | | | | |
| 40–45 | [Reserved] | Not Used | | | | | | | |
| 46 | Tach Count LSB | TCLB5 | TCLB4 | TCLB3 | TCLB2 | TCLB1 | TCLB0 | TEDGE1 | TEDGE0 |
| 47 | Tach Count MSB | TCHB13 | TCHB12 | TCHB11 | TCHB10 | TCHB9 | TCHB8 | TCHB7 | TCHB6 |
| 48 | Tach Limit LSB | TLLB7 | TLLB6 | TLLB5 | TLLB4 | TLLB3 | TLLB2 | Not Used | Not Used |
| 49 | Tach Limit MSB | TLHB15 | TLHB14 | TLHB13 | TLHB12 | TLHB11 | TLHB10 | TLHB9 | TLHB8 |
| 4A | PWM and RPM | 0 | 0 | PWPGM | PWOUT± | PWCKSL | 0 | TACH1 | TACH0 |
| 4B | Fan Spin-Up Config | 0 | 0 | SPINUP | SPNDTY1 | SPNDTY0 | SPNUPT2 | SPNUPT1 | SPNUPT0 |
| 4C | PWM Value | 0 | 0 | PWVAL5 | PWVAL4 | PWVAL3 | PWVAL2 | PWVAL1 | PWVAL0 |
| 4D | PWM Frequency | 0 | 0 | 0 | PWMF4 | PWMF3 | PWMF2 | PWMF1 | PWMF0 |
| 4E | [Reserved] | Not Used | | | | | | | |
| 4F | Lookup Table Hysteresis | 0 | 0 | 0 | LOOKH4 | LOOKH3 | LOOKH2 | LOOKH1 | LOOKH0 |
| 50–5F | Lookup Table | Lookup Table of up to 8 PWM and Temp Pairs in 8-bit Registers | | | | | | | |
| 60–BE | [Reserved] | Not Used | | | | | | | |
| BF | Rmt Diode Temp Filter | 0 | 0 | 0 | 0 | 0 | RDTF1 | RDTF0 | ALTCOMP |
| C0–FD | [Reserved] | Not Used | | | | | | | |
| FE | Manufacturer's ID | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 |
| FF | Stepping/Di e Rev. ID | 0 | 1 | 0 | 1 | 0 | 0 | 0 | 1 |

LM64 REGISTER MAP IN FUNCTIONAL ORDER

The following is a Register Map grouped in Functional Order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of named address. Reading or writing either address will access the same 8-bit register. The Fan Control and Configuration Registers are listed first, as there is a required order to setup these registers first and then setup the others. The detailed explanations of each register will follow the order shown below. POR = Power-On-Reset.

| Register [HEX] | Register Name | Read/Write | POR Default [HEX] |
|--|---------------------------------|---|--------------------|
| FAN CONTROL REGISTERS | | | |
| 4A | PWM and RPM | R/W | 20 |
| 4B | Fan Spin-Up Configuration | R/W | 3F |
| 4D | PWM Frequency | R/W | 17 |
| 4C | PWM Value | Read Only (R/W if Override Bit is Set) | 00 |
| 50–5F | Lookup Table | R/W | See Table |
| 4F | Lookup Table Hysteresis | R/W | 04 |
| CONFIGURATION REGISTER | | | |
| 03 (09) | Configuration | R/W | 00 |
| TACHOMETER COUNT AND LIMIT REGISTERS | | | |
| 46 | Tach Count LSB | Read Only | N/A |
| 47 | Tach Count MSB | Read Only | N/A |
| 48 | Tach Limit LSB | R/W | FF |
| 49 | Tach Limit MSB | R/W | FF |
| LOCAL TEMPERATURE AND LOCAL SETPOINT REGISTERS | | | |
| 00 | Local Temperature | Read Only | N/A |
| 05 (0B) | Local High Setpoint | R/W | 46 (70°) |
| REMOTE DIODE TEMPERATURE AND SETPOINT REGISTERS | | | |
| 01 | Remote Temperature MSB | Read Only | N/A |
| 10 | Remote Temperature LSB | Read Only | N/A |
| 11 | Remote Temperature Offset MSB | R/W | 00 |
| 12 | Remote Temperature Offset LSB | R/W | 00 |
| 07 (0D) | Remote High Setpoint MSB | R/W | 46 (70°C) |
| 13 | Remote High Setpoint LSB | R/W | 00 |
| 08 (0E) | Remote Low Setpoint MSB | R/W | 00 (0°C) |
| 14 | Remote Low Setpoint LSB | R/W | 00 |
| 19 | Remote TCRIT Setpoint | R/W | 55 (85°C) |
| 21 | Remote TCRIT Hys | R/W | 0A (10°C) |
| BF | Remote Diode Temperature Filter | R/W | 00 |
| CONVERSION AND ONE-SHOT REGISTERS | | | |
| 04 (0A) | Conversion Rate | R/W | 08 |
| 0F | One-Shot | Write Only | N/A |
| ALERT STATUS AND MASK REGISTERS | | | |
| 02 | ALERT Status | Read Only | N/A |
| 16 | ALERT Mask | R/W | A4 |
| ID REGISTERS | | | |
| FE | Manufacturer's ID | Read Only | 01 |
| FF | Stepping/Die Rev. ID | Read Only | 51 |
| GENERAL PURPOSE REGISTERS | | | |
| 1A | General Purpose Input | Read Only | See ⁽¹⁾ |

(1) For Register 0x1A the Power-On-Reset for the five LSB's are the logic states present on the 5 GPIOx pins.

| Register [HEX] | Register Name | Read/Write | POR Default [HEX] |
|--------------------------------------|------------------------|------------|--------------------|
| 1B | General Purpose Output | R/W | See ⁽²⁾ |
| [RESERVED] REGISTERS—NOT USED | | | |
| 06 | Not Used | N/A | N/A |
| 0C | Not Used | N/A | N/A |
| 15 | Not Used | N/A | N/A |
| 17 | Not Used | N/A | N/A |
| 18 | Not Used | N/A | N/A |
| 1C–1F | Not Used | N/A | N/A |
| 20 | Not Used | N/A | N/A |
| 22–2F | Not Used | N/A | N/A |
| 30–3F | Not Used | N/A | N/A |
| 40–45 | Not Used | N/A | N/A |
| 4E | Not Used | N/A | N/A |
| 60–BE | Not Used | N/A | N/A |
| C0–FD | Not Used | N/A | N/A |

(2) For Register 0x1B the Power-On-Reset for the five LSB's are the logic states present on the 5 GPDx pins.

LM64 INITIAL REGISTER SEQUENCE AND REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER

The following is a Register Map grouped in functional and sequence order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of named address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

LM64 Required Initial Fan Control Register Sequence

Important! The BIOS must follow the sequence below to configure the following Fan Registers for the LM64 before using any of the Fan or Tachometer or PWM registers:

| Step | [Register] _{HEX} and Setup Instructions ⁽¹⁾ |
|------|--|
| 1 | [4A] Write bits 0 and 1; 3 and 4. This includes tach settings if used, PWM internal clock select (1.4 kHz or 360 kHz) and PWM Output Polarity. |
| 2 | [4B] Write bits 0 through 5 to program the spin-up settings. |
| 3 | [4D] Write bits 0 through 4 to set the frequency settings. This works with the PWM internal clock select. |
| 4 | Choose, then write, only one of the following: A. [4F–5F] the Lookup Table, or B. [4C] the PWM value bits 0 through 5. |
| 5 | If Step 4A, Lookup Table, was chosen and written then write [4A] bit 5 = 0. |

(1) All other registers can be written at any time after the above sequence.

LM64 REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER

Fan Control Registers

| Address Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|-----------|-------------------------|---|
| 4A_{HEX} PWM AND RPM REGISTER | | | | | |
| 4A | R/W | 7:6 | 00 | PWM Program | These bits are unused and always set to 0. |
| | | 5 | 1 | | 0: the PWM Value (register 4C) and the Lookup Table (50–5F) are read-only. The PWM value (0 to 100%) is determined by the current remote diode temperature and the Lookup Table, and can be read from the PWM value register. 1: the PWM value (register 4C) and the Lookup Table (Register 50–5F) are read/write enabled. Writing the PWM Value register will set the PWM output. This is also the state during which the Lookup Table can be written. |
| | | 4 | 0 | PWM Output Polarity | 0: the PWM output pin will be 0 V for fan OFF and open for fan ON. 1: the PWM output pin will be open for fan OFF and 0 V for fan ON. |
| | | 3 | 0 | PWM Clock Select | if 0, the master PWM clock is 360 kHz if 1, the master PWM clock is 1.4 kHz. |
| | | 2 | 0 | [Reserved] | Always write 0 to this bit. |
| | | 1:0 | 00 | Tachometer Mode | 00: Traditional tach input monitor, false readings when under minimum detectable RPM. 01: Traditional tach input monitor, FFFF reading when under minimum detectable RPM. 10: Most accurate readings, FFFF reading when under minimum detectable RPM. 11: Least effort on programmed PWM of fan, FFFF reading when under minimum detectable RPM. Note: If the PWM Clock is 360 kHz, mode 00 is used regardless of the setting of these two bits. |
| 4B_{HEX} FAN SPIN-UP CONFIGURATION REGISTER | | | | | |
| 4B | R/W | 7:6 | 0 | Fast Tachometer Spin-Up | These bits are unused and always set to 0 |
| | | 5 | 1 | | If 0, the fan spin-up uses the duty cycle and spin-up time, bits 0–4. If 1, the LM64 sets the PWM output to 100% until the spin-up times out (per bits 0–2) or the minimum desired RPM has been reached (per the Tachometer Setpoint setting) using the tachometer input, whichever happens first. This bit overrides the PWM Spin-Up Duty Cycle register (bits 4:3)—PWM output is always 100%. If PWM Spin-Up Time (bits 2:0) = 000, the Spin-Up cycle is bypassed, regardless of the state of this bit. |
| | | 4:3 | 11 | PWM Spin-Up Duty Cycle | 00: Spin-Up cycle bypassed (no Spin-Up), unless Fast Tachometer Terminated Spin-Up (bit 5) is set. 01: 50% 10: 75%–81% Depends on PWM Frequency. See Applications Notes . 11: 100% |
| | | 2:0 | 111 | PWM Spin-Up Time | 000: Spin-Up cycle bypassed (No Spin-Up) 001: 0.05 seconds 010: 0.1 s 011: 0.2 s 100: 0.4 s 101: 0.8 s 110: 1.6 s 111: 3.2 s |
| 4D_{HEX} FAN PWM FREQUENCY REGISTER | | | | | |
| 4D | R/W | 7:5 | 000 | PWM Frequency | These bits are unused and always set to 0 |
| | | 4:0 | 10111 | | The PWM Frequency = PWM_Clock / 2n, where PWM_Clock = 360 kHz or 1.4 kHz (per the PWM Clock Select bit in Register 4A), and n = value of the register. Note: n = 0 is mapped to n = 1. See the Applications Notes at the end of this datasheet. |

| Address Hex | Read/Write | Bits | POR Value | Name | Description |
|--|---|------|----------------------------------|--|--|
| 4C_{HEX} PWM VALUE REGISTER | | | | | |
| 4C | Read (Write only if reg 4A bit 5 = 1.) | 7:6 | 00 | PWM Value | These bits are unused and always set to 0 |
| | | 5:0 | 000000 | | If PWM Program (register 4A, bit 5) = 0 this register is read only and reflects the LM64's current PWM value from the Lookup Table. If PWM Program (register 4A, bit 5) = 1, this register is read/write and the desired PWM value is written directly to this register, instead of from the Lookup Table, for direct fan speed control. This register will read 0 during the Spin-Up cycle. See Application Notes section at the end of this datasheet for more information regarding the PWM Value and Duty Cycle in %. |
| 50_{HEX} to 5F_{HEX} LOOKUP TABLE (7 Bits for Temperature and 6 Bits for PWM for each Temperature/PWM Pair) | | | | | |
| 50 | Read. (Write only if reg 4A bit 5 = 1.) | 7 | 0 | Lookup Table Temperature Entry 1 | This bit is unused and always set to 0. |
| | | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 51. |
| 51 | | 7:6 | 00 | Lookup Table PWM Entry 1 | These bits are unused and always set to 0. |
| | | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 50. |
| 52 | | 7 | 0 | Lookup Table Temperature Entry 2 | This bit is unused and always set to 0. |
| | | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 53. |
| 53 | | 7:6 | 00 | Lookup Table PWM Entry 2 | These bits are unused and always set to 0. |
| | | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 52. |
| 54 | | 7 | 0 | Lookup Table Temperature Entry 3 | This bit is unused and always set to 0. |
| | | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 55. |
| 55 | | 7:6 | 00 | Lookup Table PWM Entry 3 | These bits are unused and always set to 0. |
| | | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 54. |
| 56 | | 7 | 0 | Lookup Table Temperature Entry 4 | This bit is unused and always set to 0. |
| | | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 57. |
| 57 | | 7:6 | 00 | Lookup Table PWM Entry 4 | These bits are unused and always set to 0. |
| | | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 56. |
| 58 | | 7 | 0 | Lookup Table Temperature Entry 5 | This bit is unused and always set to 0. |
| | | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 59. |
| 59 | | 7:6 | 00 | Lookup Table PWM Entry 5 | These bits are unused and always set to 0. |
| | | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 58. |
| 5A | 7 | 0 | Lookup Table Temperature Entry 6 | This bit is unused and always set to 0. | |
| | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5B. | |
| 5B | 7:6 | 00 | Lookup Table PWM Entry 6 | These bits are unused and always set to 0. | |
| | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 5A. | |
| 5C | 7 | 0 | Lookup Table Temperature Entry 7 | This bit is unused and always set to 0. | |
| | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5D. | |
| 5D | 7:6 | 00 | Lookup Table PWM Entry 7 | These bits are unused and always set to 0. | |
| | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 5C. | |
| 5E | 7 | 0 | Lookup Table Temperature Entry 8 | This bit is unused and always set to 0. | |
| | 6:0 | 0x7F | | If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5F. | |
| 5F | 7:6 | 00 | Lookup Table PWM Entry 8 | These bits are unused and always set to 0. | |
| | 5:0 | 0x3F | | The PWM value corresponding to the temperature limit in register 5E. | |

| Address Hex | Read/Write | Bits | POR Value | Name | Description |
|---|------------|------|-----------|-------------------------|--|
| 4F_{HEX} LOOKUP TABLE HYSTERESIS | | | | | |
| 4F | R/W | 7:5 | 000 | Lookup Table Hysteresis | These bits are unused and always set to 0 |
| | | 4:0 | 00100 | | The amount of hysteresis applied to the Lookup Table. (1 LSB = 1°C). |

Configuration Register

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|---|------------|------|-----------|------------------------|--|
| 03 (09)_{HEX} CONFIGURATION REGISTER | | | | | |
| 03 (09) | R/W | 7 | 0 | ALERT Mask | When this bit is a 0, ALERT interrupts are enabled. When this bit is set to a 1, ALERT interrupts are masked, and the $\overline{\text{ALERT}}$ pin is always in a high impedance (open) state. |
| | | 6 | 0 | STANDBY | When this bit is a 0, the LM64 is in operational mode, converting, comparing, and updating the PWM output continuously. When this bit is a 1, the LM64 enters a low power standby mode. In STANDBY, continuous conversions are stopped, but a conversion/comparison cycle may be initiated by writing any value to register 0x0F. Operation of the PWM output in STANDBY depends on the setting of bit 5 in this register. |
| | | 5 | 0 | PWM Disable in STANDBY | When this bit is a 0, the LM64's PWM output continues to output the current fan control signal while in STANDBY. When this bit is a 1, the PWM output is disabled (as defined by the PWM polarity bit) while in STANDBY. |
| | | 4:1 | 0000 | | These bits are unused and always set to 0. |
| | | 0 | 0 | RDTs Fault Queue | 0: an ALERT will be generated if any Remote Diode conversion result is above the Remote High Set Point or below the Remote Low Setpoint . 1: an ALERT will be generated only if three consecutive Remote Diode conversions are above the Remote High Set Point or below the Remote Low Setpoint . |

Tachometer Count And Limit Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description | | |
|---|------------|------|-----------|------------------------|--|-----------------------|----------------------------|
| 47_{HEX} TACHOMETER COUNT (MSB) and 46_{HEX} TACHOMETER COUNT (LSB) REGISTERS (16 bits: Read LSB first to lock MSB and ensure MSB and LSB are from the same reading) | | | | | | | |
| 47 | Read Only | 7:0 | N/A | Tachometer Count (MSB) | These registers contain the current 16-bit Tachometer Count, representing the period of time between tach pulses. Note that the 16-bit tachometer MSB and LSB are reversed from the 16-bit temperature readings | | |
| 46 | Read Only | 7:2 | N/A | Tachometer Count (MSB) | | | |
| | Read Only | 1:0 | 00 | Tachometer Edge Count | Bits: | Edges Used | Tach_Count_Multiple |
| | | | | | 00: | Reserved - do not use | |
| | | | | | 01: | 2 | 4 |
| | | | | | 10: | 2 | 2 |
| 11: | 5 | 1 | | | | | |
| Note: If PWM_Clock_Select = 360 kHz, then Tach_Count_Multiple = 1 regardless of the setting of these bits. | | | | | | | |
| 49_{HEX} TACHOMETER LIMIT (MSB) and 48_{HEX} TACHOMETER LIMIT (LSB) REGISTERS | | | | | | | |
| 49 | R/W | 7:0 | 0xFF | Tachometer Limit (MSB) | These registers contain the current 16-bit Tachometer Count, representing the period of time between tach pulses. Fan RPM = $(f * 5,400,000) / (\text{Tachometer Count})$, where $f = 1$ for 2 pulses/rev fan; $f = 2$ for 1 pulse/rev fan; and $f = 2/3$ for 3 pulses/rev fan. See the Application Notes section for more tachometer information. Note that the 16-bit tachometer MSB and LSB are reversed from the 16 bit temperature readings. | | |
| 48 | R/W | 7:2 | 0xFF | Tachometer Limit (LSB) | | | |
| | R/W | 1:0 | | [Reserved] | | Not Used. | |

Local Temperature And Local High Setpoint Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|------------|-----------------------------------|---------------------------------------|
| 00_{HEX} LOCAL TEMPERATURE REGISTER (8-bits) | | | | | |
| 00 | Read Only | 7:0 | N/A | Local Temperature Reading (8-bit) | 8-bit temperature of the LM64. |
| 05 (0B)_{HEX} LOCAL HIGH SETPOINT REGISTER (8-bits) | | | | | |
| 05 | R/W | 7:0 | 0x46 (70°) | Local HIGH Setpoint | High Setpoint for the internal diode. |

Remote Diode Temperature, Offset And Setpoint Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|-------------|------------|------|-------------|--|--|
| 01 | Read Only | 7:0 | N/A | Remote Diode Temperature Reading (MSB) | This is the MSB of the LM64 remote diode temperature value, 2's complement. Bit 7 is the sign bit, bit 6 has a weight 64°C, and bit 0 has a weight of 1°C. Read this byte first. The actual remote diode temperature is 16°C higher than the values in registers 0x01 and 0x10. |
| 10 | Read Only | 7:5 | N/A | Remote Diode Temperature Reading (LSB) | This is the LSB of the LM64 remote diode temperature value, in 2's complement. Bit 7 has a weight 0.5°C, bit 6 has a weight of 0.25°C, and bit 5 has a weight of 0.125°C. The actual remote diode temperature is 16°C higher than the values in registers 0x01 and 0x10. |
| | | 4:0 | 00 | | Always 00. |
| 11 | R/W | 7:5 | 00 | Remote Temperature OFFSET (MSB) | These registers contain the offset value added to, or subtracted from, the remote diode's reading to compensate for the different non-ideality factors of different processors, diodes, etc. The 2's complement value, in these registers is added to the output of the LM64's ADC to form the temperature reading contained in registers 01 and 10. |
| 12 | R/W | 7:5 | 00 | Remote Temperature OFFSET (LSB) | Always 00. |
| | | 4:0 | 00 | | Always 00. |
| 07 (0D) | R/W | 7:0 | 0x46 (70°C) | Remote HIGH Setpoint (MSB) | High setpoint temperature for remote diode. Same format as Remote Temperature Reading (registers 01 and 10). |
| 13 | R/W | 7:5 | 00 | Remote HIGH Setpoint (LSB) | Always 00. |
| | | 4:0 | 00 | | Always 00. |
| 08 (0E) | R/W | 7:0 | 00 (0°C) | Remote LOW Setpoint (MSB) | Low setpoint temperature for remote diode. Same format as Remote Temperature Reading (registers 01 and 10). |
| 14 | R/W | 7:5 | 00 | Remote LOW Setpoint (LSB) | Always 00. |
| | | 4:0 | 00 | | Always 00. |
| 19 | R/W | 7:0 | 0x55 (85°C) | Remote Diode T_CRIT Limit | This 8-bit integer storing the T_CRIT limit is initially 85°C (101°C actual remote T_Crit limit). This value can be changed at any time after power-up. |
| 21 | R/W | 7:0 | 0x0A (10°C) | Remote Diode T_CRIT Hysteresis | 8-bit integer storing T_CRIT hysteresis. T_CRIT stays activated until the remote diode temperature goes below [(T_CRIT Limit)–(T_CRIT Hysteresis)]. |
| BF | R/W | 7:3 | 00000 | | These bits are unused and should always set to 0. |
| | | 2:1 | 00 | Remote Diode Temperature Filter | 00: Filter Disabled 01: Filter Level 1 (minimal filtering, same as 10) 10: Filter Level 1 (minimal filtering, same as 01) 11: Filter Level 2 (maximum filtering) |
| | | 0 | 0 | Comparator Mode | 0: the $\overline{\text{ALERT}}$ pin functions as an Interrupt or ARA mode. 1: the ALERT pin behaves as a comparator, asserting itself when an ALERT condition exists, de-asserting itself when the ALERT condition goes away. |

ALERT Status And Mask Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|-----------|--------------------------|---|
| 02_{HEX} ALERT STATUS REGISTER (8-bits) (All Alarms are latched until read, then cleared if alarm condition was removed at the time of the read.) | | | | | |
| 0x02 | Read Only | 7 | 0 | Busy | When this bit is a 0, the ADC is not converting. When this bit is set to a 1, the ADC is performing a conversion. This bit does not affect ALERT status. |
| | | 6 | 0 | Local High Alarm | When this bit is a 0, the internal temperature of the LM64 is at or below the Local High Setpoint. When this bit is a 1, the internal temperature of the LM64 is above the Local High Setpoint, and an ALERT is triggered. |
| | | 5 | 0 | | This bit is unused and always read as 0. |
| | | 4 | 0 | Remote High Alarm | When this bit is a 0, the temperature of the Remote Diode is at or below the Remote High Setpoint. When this bit is a 1, the temperature of the Remote Diode is above the Remote High Setpoint, and an ALERT is triggered. |
| | | 3 | 0 | Remote Low Alarm | When this bit is a 0, the temperature of the Remote Diode is at or above the Remote Low Setpoint. When this bit is a 1, the temperature of the Remote Diode is below the Remote Low Setpoint, and an ALERT is triggered. |
| | | 2 | 0 | Remote Diode Fault Alarm | When this bit is a 0, the Remote Diode appears to be correctly connected. When this bit is a 1, the Remote Diode may be disconnected or shorted. This Alarm does not trigger an ALERT. |
| | | 1 | 0 | Remote T_CRIT Alarm | When this bit is a 0, the temperature of the Remote Diode is at or below the T_CRIT Limit. When this bit is a 1, the temperature of the Remote Diode is above the T_CRIT Limit, and an ALERT is triggered. |
| | | 0 | 0 | Tach Alarm | When this bit is a 0, the Tachometer count is lower than or equal to the Tachometer Limit (the RPM of the fan is greater than or equal to the minimum desired RPM). When this bit is a 1, the Tachometer count is higher than the Tachometer Limit (the RPM of the fan is less than the minimum desired RPM), and an ALERT is triggered. |
| 16_{HEX} ALERT MASK REGISTER (8-bits) | | | | | |
| 16 | R/W | 7 | 1 | | This bit is unused and always read as 1. |
| | | 6 | 0 | Local High Alarm Mask | When this bit is a 0, a Local High Alarm event will generate an ALERT. When this bit is a 1, a Local High Alarm will not generate an ALERT. |
| | | 5 | 1 | | This bit is unused and always read as 1. |
| | | 4 | 0 | Remote High Alarm Mask | When this bit is a 0, Remote High Alarm event will generate an ALERT. When this bit is a 1, a Remote High Alarm event will not generate an ALERT. |
| | | 3 | 0 | Remote Low Alarm Mask | When this bit is a 0, a Remote Low Alarm event will generate an ALERT. When this bit is a 1, a Remote Low Alarm event will not generate an ALERT. |
| | | 2 | 1 | | This bit is unused and always read as 1. |
| | | 1 | 0 | Remote T_CRIT Alarm Mask | When this bit is a 0, a Remote T_CRIT event will generate an ALERT. When this bit is a 1, a Remote T_CRIT event will not generate an ALERT. |
| | | 0 | 0 | Tach Alarm Mask | When this bit is a 0, a Tach Alarm event will generate an ALERT. When this bit is a 1, a Tach Alarm event will not generate an ALERT. |

Conversion Rate And One-Shot Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|-----------|------------------|---|
| 04 (0A)_{HEX} CONVERSION RATE REGISTER (8-bits) | | | | | |
| 04 (0A) | R/W | 7:0 | 0x08 | Conversion Rate | Sets the conversion rate of the LM64. 00000000 = 0.0625 Hz 00000001 = 0.125 Hz 00000010 = 0.25 Hz 00000011 = 0.5 Hz 00000100 = 1 Hz 00000101 = 2 Hz 00000110 = 4 Hz 00000111 = 8 Hz 00001000 = 16 Hz 00001001 = 32 Hz All other values = 32 Hz |
| 04 (0A)_{HEX} ONE-SHOT REGISTER (8-bits) | | | | | |
| 0F | Write Only | 7:0 | N/A | One Shot Trigger | With the LM64 in the STANDBY mode a single write to this register will initiate one complete temperature conversion cycle. |

ID Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|-----------|--------------------------|--------------------------|
| FF_{HEX} STEPPING / DIE REVISION ID REGISTER (8-bits) | | | | | |
| FF | Read Only | 7:0 | 0x51 | Stepping/Die Revision ID | Version of LM64 |
| FE_{HEX} MANUFACTURER'S ID REGISTER (8-bits) | | | | | |
| FE | Read Only | 7:0 | 0x01 | Manufacturer's ID | 0x01 = Texas Instruments |

General Purpose Registers

| ADDRESS Hex | Read/Write | Bits | POR Value | Name | Description |
|--|------------|------|--------------------|------------------------|--|
| 1A_{HEX} GENERAL PURPOSE INPUT REGISTER (8-bits) | | | | | |
| 1A | Read Only | 7:5 | 000 | General Purpose Input | These bits are unused and always set to 0. |
| | | 4:0 | See ⁽¹⁾ | | These 5 bits reflect the logic states of the GPIOx pins. |
| 1B_{HEX} GENERAL PURPOSE OUTPUT REGISTER (8-bits) | | | | | |
| 1B | R/W | 7:5 | 000 | General Purpose Output | These bits are unused and always set to 0. |
| | | 4:0 | See ⁽²⁾ | | These 5 bits reflect the GPI register bits [4:0] except for Power-On-Default when they are the 5 logic states of the General Purpose Default (GPD) input pins. |

(1) For Register 0x1A the Power-On-Reset for the five LSB's are the logic states present on the 5 GPIOx pins.

(2) For Register 0x1B the Power-On-Reset for the five LSB's are the logic states present on the 5 GPDx pins.

Application Notes

FAN CONTROL DUTY CYCLE VS. REGISTER SETTINGS AND FREQUENCY

| PWM Freq 4D [4:0] | Step Resolution, % | PWM Value 4D [5:0] for 100% | PWM Value 4C [5:0] for about 75% | PWM Value 4C [5:0] for 50% | PWM Freq at 360 kHz Internal Clock, kHz | PWM Freq at 1.4 kHz Internal Clock, Hz | Actual Duty Cycle, % When 75% is Selected |
|-------------------|----------------------------------|-----------------------------|----------------------------------|----------------------------|---|--|---|
| 0 | Address 0 is mapped to Address 1 | | | | | | |
| 1 | 50 | 2 | 1 | 1 | 180.0 | 703.1 | 50.0 |
| 2 | 25 | 4 | 3 | 2 | 90.00 | 351.6 | 75.0 |
| 3 | 16.7 | 6 | 5 | 3 | 60.00 | 234.4 | 83.3 |
| 4 | 12.5 | 8 | 6 | 4 | 45.00 | 175.8 | 75.0 |
| 5 | 10.0 | 10 | 8 | 5 | 36.00 | 140.6 | 80.0 |
| 6 | 8.33 | 12 | 9 | 6 | 30.00 | 117.2 | 75.0 |
| 7 | 7.14 | 14 | 11 | 7 | 25.71 | 100.4 | 78.6 |
| 8 | 6.25 | 16 | 12 | 8 | 22.50 | 87.9 | 75.0 |
| 9 | 5.56 | 18 | 14 | 9 | 20.00 | 78.1 | 77.8 |
| 10 | 5.00 | 20 | 15 | 10 | 18.00 | 70.3 | 75.0 |
| 11 | 4.54 | 22 | 17 | 11 | 16.36 | 63.9 | 77.27 |
| 12 | 4.16 | 24 | 18 | 12 | 15.00 | 58.6 | 75.00 |
| 13 | 3.85 | 26 | 20 | 13 | 13.85 | 54.1 | 76.92 |
| 14 | 3.57 | 28 | 21 | 14 | 12.86 | 50.2 | 75.00 |
| 15 | 3.33 | 30 | 23 | 15 | 12.00 | 46.9 | 76.67 |
| 16 | 3.13 | 32 | 24 | 16 | 11.25 | 43.9 | 75.00 |
| 17 | 2.94 | 34 | 26 | 17 | 10.59 | 41.4 | 76.47 |
| 18 | 2.78 | 36 | 27 | 18 | 10.00 | 39.1 | 75.00 |
| 19 | 2.63 | 38 | 29 | 19 | 9.47 | 37.0 | 76.32 |
| 20 | 2.50 | 40 | 30 | 20 | 9.00 | 35.2 | 75.00 |
| 21 | 2.38 | 42 | 32 | 21 | 8.57 | 33.5 | 76.19 |
| 22 | 2.27 | 44 | 33 | 22 | 8.18 | 32.0 | 75.00 |
| 23 | 2.17 | 46 | 35 | 23 | 7.82 | 30.6 | 76.09 |
| 24 | 2.08 | 48 | 36 | 24 | 7.50 | 29.3 | 75.00 |
| 25 | 2.00 | 50 | 38 | 25 | 7.20 | 28.1 | 76.00 |
| 26 | 1.92 | 52 | 39 | 26 | 6.92 | 27.0 | 75.00 |
| 27 | 1.85 | 54 | 41 | 27 | 6.67 | 26.0 | 75.93 |
| 28 | 1.79 | 56 | 42 | 28 | 6.42 | 25.1 | 75.00 |
| 29 | 1.72 | 58 | 44 | 29 | 6.21 | 24.2 | 75.86 |
| 30 | 1.67 | 60 | 45 | 30 | 6.00 | 23.4 | 75.00 |
| 31 | 1.61 | 62 | 47 | 31 | 5.81 | 22.7 | 75.81 |

Computing Duty Cycles for a Given Frequency

Select a PWM Frequency from the first column corresponding to the desired actual frequency in columns 6 or 7. Note the PWM Value for 100% Duty Cycle.

Find the Duty Cycle by taking the PWM Value of Register 4C and computing:

$$DutyCycle \text{ } _{(\%)} = \frac{PWM \text{ } _{Value}}{PWM \text{ } _{Value} \text{ } _{for} \text{ } _{100\%}} \times 100\% \quad (1)$$

Example: For a PWM Frequency of 24, a PWM Value at 100% = 48 and PWM Value actual = 28, then the Duty Cycle is $(28/48) \times 100\% = 58.3\%$.

USE OF THE LOOKUP TABLE FOR NON-LINEAR PWM VALUES VS TEMPERATURE

The Lookup Table, Registers 50 through 5F, can be used to create a non-linear PWM vs Temperature curve that could be used to reduce the acoustic noise from processor fan due to linear or step transfer functions. An example is given below:

EXAMPLE:

In a particular system it was found that the best acoustic fan noise performance was found to occur when the PWM vs Temperature transfer function curve was parabolic in shape.

From 25°C to 105°C the fan is to go from 20% to 100%. Since there are 8 steps to the Lookup Table we will break up the Temperature range into 8 separate temperatures. For the 80°C over 8-steps = 10°C per step. This takes care of the x-axis.

For the PWM Value, we first select the PWM Frequency. In this example we will make the PWM Frequency (Register 4C) 20.

For 100% Duty Cycle then, the PWM value is 40. For 20% the minimum is $40 \times (0.2) = 8$.

We can then arrange the PWM, Temperature pairs in a parabolic fashion in the form of $y = 0.005 \cdot (x - 25)^2 + 8$

| Temperature | PWM Value Calculated | Closest PWM Value |
|-------------|----------------------|-------------------|
| 25 | 8.0 | 8 |
| 35 | 8.5 | 9 |
| 45 | 10.0 | 10 |
| 55 | 12.5 | 13 |
| 65 | 16.0 | 16 |
| 75 | 20.5 | 21 |
| 85 | 26.0 | 26 |
| 95 | 32.5 | 33 |
| 105 | 40.0 | 40 |

We can then program the Lookup Table with the temperature and Closest PWM Values required for the curve required in our example.

NON-IDEALITY FACTOR AND TEMPERATURE ACCURACY

The LM64 can be applied to remote diode sensing in the same way as other integrated-circuit temperature sensors. It can be soldered to a printed-circuit board, and because the path of best thermal conductivity is between the die and the pins, its temperature will effectively be that of the printed-circuit board lands and traces soldered to its pins. This presumes that the ambient air temperature is nearly the same as the surface temperature of the printed-circuit board. If the air temperature is much higher or lower than the surface temperature, the actual temperature of the LM64 die will be an intermediate temperature between the surface and air temperatures. Again, the primary thermal conduction path is through the leads, so the circuit board surface temperature will contribute to the die temperature much more than the air temperature.

To measure the temperature external to the die use a remote diode. This diode can be located on the die of the target IC, such as a CPU processor chip, allowing measurement of the IC's temperature, independent of the LM64's temperature. The LM64 has been optimized for use with a MMBT3904 diode-connected transistor.

A discrete diode can also be used to sense the temperature of external objects or ambient air. Remember that a discrete diode's temperature will be affected, and often dominated by, the temperature of its leads.

Most silicon diodes do not lend themselves well to this application. It is recommended that a diode-connected MMBT3904 transistor be used. The base of the transistor is connected to the collector and becomes the anode. The emitter is the cathode.

Diode Non_Ideality

When a transistor is connected to a diode the following relationship holds for V_{be} , T , and I_F :

$$I_F = I_S \cdot \left[e^{\left(\frac{V_{be}}{\eta \cdot V_T} \right)} - 1 \right] \quad (2)$$

where

$$V_T = \frac{kT}{q}$$

- $q = 1.6 \times 10^{-19}$ Coulombs (the electron charge)
- T = Absolute Temperature in Kelvin
- $k = 1.38 \times 10^{-23}$ joules/K (Boltzmann's constant)
- η is the non-ideality factor of the manufacturing process used to make the thermal diode
- I_S = Saturation Current and is process dependent
- I_f = Forward Current through the base emitter junction
- V_{be} = Base Emitter Voltage Drop

(3)

In the active region, the -1 term is negligible and may be eliminated, yielding the following equation

$$I_F = I_S \cdot \left[e^{\left(\frac{V_{be}}{\eta \cdot V_T} \right)} \right] \quad (4)$$

In the above equation, η and I_S are dependent upon the process that was used in the fabrication of the particular diode. By forcing two currents with a very controlled ratio (N) and measuring the resulting voltage difference, it is possible to eliminate the I_S term. Solving for the forward voltage difference yields the relationship:

$$\Delta V_{be} = \eta \left(\frac{kT}{q} \right) \cdot \ln(N) \quad (5)$$

The non-ideality factor, η , is the only other parameter not accounted for and depends on the diode that is used for measurement. Since ΔV_{be} is proportional to both η and T , the variations in η cannot be distinguished from variations in temperature. Since the temperature sensor does not control the non-ideality factor, it will directly add to the inaccuracy of the sensor.

For example, if a processor manufacturer specifies a $\pm 0.1\%$ variation in η from part to part. As an example, assume that a temperature sensor has an accuracy specification of $\pm 1^\circ\text{C}$ at room temperature of 25°C . The resulting accuracy will be:

$$T_{ACC} = \pm 1^\circ\text{C} + (\pm 0.1\% \text{ of } 298^\circ\text{K}) = \pm 1.3^\circ\text{C}$$

The additional inaccuracy in the temperature measurement caused by η , can be eliminated if each temperature sensor is calibrated with the remote diode that it will be paired with. Refer to the processor datasheet for the non-ideality factor.

Compensating for Diode Non-Ideality

In order to compensate for the errors introduced by non-ideality, the temperature sensor is calibrated for a particular processor. Texas Instruments temperature sensors are always calibrated to the typical non-ideality of a particular processor type.

The LM64 is calibrated for a MMBT3904 diode-connected transistor.

When a temperature sensor, calibrated for a specific type of processor is used with a different processor type or a given processor type has a non-ideality that strays from the typical value, errors are introduced.

Temperature errors associated with non-ideality may be introduced in a specific temperature range of concern through the use of the Temperature Offset Registers 11_{HEX} and 12_{HEX}.

The user is encouraged to send an e-mail to hardware.monitor.team@nsc.com to further request information on our recommended setting of the offset register for different processor types.

COMPUTING RPM OF THE FAN FROM THE TACH COUNT

The Tach Count Registers 46_{HEX} and 47_{HEX} count the number of periods of the 90 kHz tachometer clock in the LM64 for the tachometer input from the fan assuming a 2 pulse per revolution fan tachometer, such as the fans supplied with the Pentium 4 boxed processors. The RPM of the fan can be computed from the Tach Count Registers 46_{HEX} and 47_{HEX}. This can best be shown through an example.

Example:

Given: the fan used has a tachometer output with 2 per revolution.

Let:

Register 46 (LSB) is BF_{HEX} = Decimal (11 x 16) + 15 = 191 and

Register 47 (MSB) is 7_{HEX} = Decimal (7 x 256) = 1792.

The total Tach Count, in decimal, is 191 + 1792 = **1983**.

The RPM is computed using the formula

$$Fan _ RPM = \frac{f \times 5,400,000}{Total _ Tach _ Count _ (Decimal)}, \tag{6}$$

where

f = 1 for 2 pulses/rev fan tachometer output;

f = 2 for 1 pulse/rev fan tachometer output, and

f = 2 / 3 for 3 pulses/rev fan tachometer output

For our example

$$Fan _ RPM = \frac{1 \times 5,400,000}{1983} = 2723 _ RPM \tag{7}$$

PCB LAYOUT FOR MINIMIZING NOISE

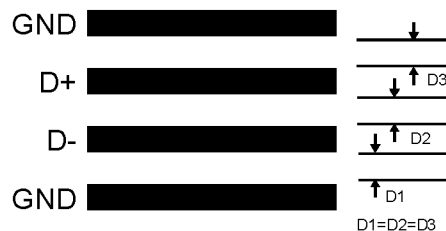


Figure 12. Ideal Diode Trace Layout

In a noisy environment, such as a processor mother board, layout considerations are very critical. Noise induced on traces running between the remote temperature diode sensor and the LM64 can cause temperature conversion errors. Keep in mind that the signal level the LM64 is trying to measure is in microvolts. The following guidelines should be followed:

1. Place a 0.1 μF power supply bypass capacitor as close as possible to the V_{DD} pin and the recommended 2.2 nF capacitor as close as possible to the LM64's D+ and D- pins. Make sure the traces to the 2.2 nF capacitor are matched.
2. Ideally, the LM64 should be placed within 10 cm of the Processor diode pins with the traces being as straight, short and identical as possible. Trace resistance of 1 Ω can cause as much as 1°C of error. This

error can be compensated by using the Remote Temperature Offset Registers, since the value placed in these registers will automatically be subtracted from or added to the remote temperature reading.


3. Diode traces should be surrounded by a GND guard ring to either side, above and below if possible. This GND guard should not be between the D+ and D- lines. In the event that noise does couple to the diode lines it would be ideal if it is coupled common mode. That is equally to the D+ and D- lines.
4. Avoid routing diode traces in close proximity to power supply switching or filtering inductors.
5. Avoid running diode traces close to or parallel to high speed digital and bus lines. Diode traces should be kept at least 2 cm apart from the high speed digital traces.
6. If it is necessary to cross high speed digital traces, the diode traces and the high speed digital traces should cross at a 90 degree angle.
7. The ideal place to connect the LM64's GND pin is as close as possible to the Processor's GND associated with the sense diode.
8. Leakage current between D+ and GND should be kept to a minimum. One nano-ampere of leakage can cause as much as 1°C of error in the diode temperature reading. Keeping the printed circuit board as clean as possible will minimize leakage current.

Noise coupling into the digital lines greater than 400 mVp-p (typical hysteresis) and undershoot less than 500 mV below GND, may prevent successful SMBus communication with the LM64. SMBus no acknowledge is the most common symptom, causing unnecessary traffic on the bus. Although the SMBus maximum frequency of communication is rather low (100 kHz max), care still needs to be taken to ensure proper termination within a system with multiple parts on the bus and long printed circuit board traces. An RC lowpass filter with a 3 dB corner frequency of about 40 MHz is included on the LM64's SMBCLK input. Additional resistance can be added in series with the SMBData and SMBCLK lines to further help filter noise and ringing. Minimize noise coupling by keeping digital traces out of switching power supply areas as well as ensuring that digital lines containing high speed data communications cross at right angles to the SMBData and SMBCLK lines.

REVISION HISTORY

| Changes from Original (March 2013) to Revision A | Page |
|--|--------------------------|
| <hr/> <ul style="list-style-type: none">• Changed layout of National Data Sheet to TI format | <hr/> 32 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|---|
| LM64CILQ-F/NOPB | ACTIVE | WQFN | NHW | 24 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-3-260C-168 HR | 0 to 125 | 64CILQF |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM64CILQ-F/NOPB | WQFN | NHW | 24 | 1000 | 178.0 | 12.4 | 4.3 | 5.3 | 1.3 | 8.0 | 12.0 | Q1 |

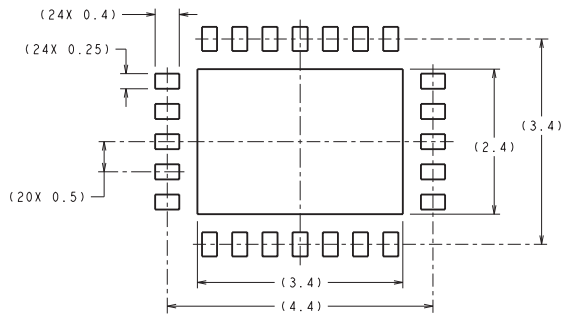
TAPE AND REEL BOX DIMENSIONS



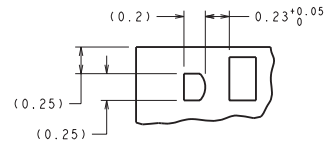
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM64CILQ-F/NOPB | WQFN | NHW | 24 | 1000 | 210.0 | 185.0 | 35.0 |

NHW0024B

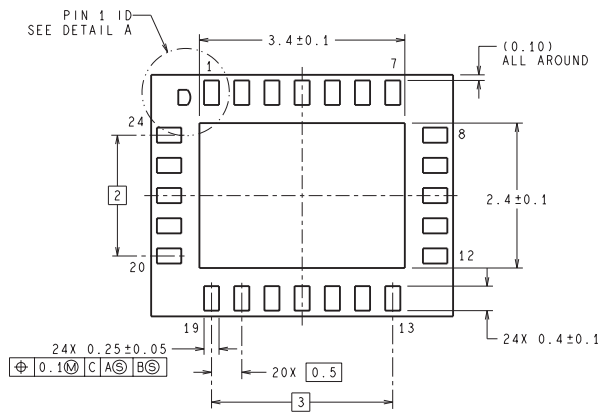
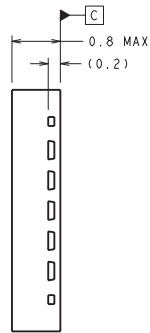
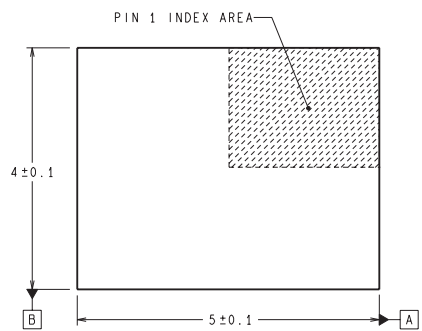


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



DETAIL A

DIMENSIONS ARE IN MILLIMETERS
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LQA24A (Rev B)

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